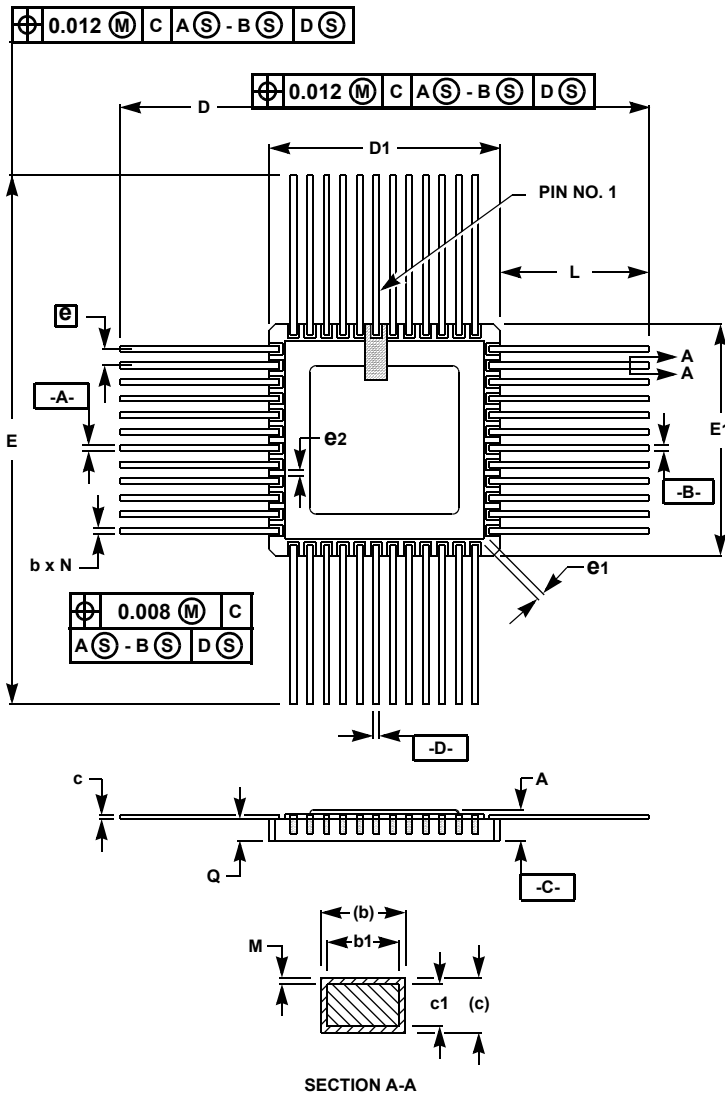


Ceramic Quad Flatpack (CQFP)



R68.A

68 LEAD CERAMIC QUAD FLATPACK PACKAGE

| SYMBOL | INCHES | | MILLIMETERS | | NOTES |
|--------|-----------|--------|-------------|-------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.075 | 0.135 | 1.91 | 3.43 | - |
| b | 0.016 | 0.023 | 0.41 | 0.58 | 2 |
| b1 | 0.016 | 0.020 | 0.41 | 0.51 | 2 |
| c | 0.008 | 0.015 | 0.20 | 0.38 | 2 |
| c1 | 0.008 | 0.012 | 0.20 | 0.31 | 2 |
| D | 1.640 | 1.870 | 41.66 | 47.50 | - |
| E | 1.640 | 1.870 | 41.66 | 47.50 | - |
| D1 | 0.940 | 0.960 | 23.88 | 24.38 | - |
| E1 | 0.940 | 0.960 | 23.88 | 24.38 | 4 |
| e | 0.050 BSC | | 1.27 BSC | | - |
| e1 | 0.012 | - | 0.31 | - | - |
| e2 | 0.012 | - | 0.31 | - | - |
| L | 0.350 | 0.450 | 8.89 | 11.43 | - |
| Q | 0.070 | 0.120 | 1.78 | 3.05 | 6 |
| M | - | 0.0015 | - | 0.04 | 2 |
| N | 68 | | 68 | | 3 |

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NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. N is the maximum number of terminal positions.
4. Measure dimension e1 at all four corners.
5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
6. Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
7. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
8. Controlling dimension: Inch.